# Integrated Passive Compor

The Syfer Balanced Line Chip is a 3 terminal EMI chip device. The revolutionary design provides simultaneous line-to-line and line-toground filtering, using a single ceramic chip. In this way, differential and common mode filtering are provided in one device. Capable of replacing 2 or more conventional devices, it is ideal for balanced lines, twisted pairs and dc motors, in automotive, audio, sensor and other applications.

These filters can prove invaluable in meeting stringent EMC demands particularly in automotive applications.



#### **Specifications**

Dielectric **Electrical Configuration Capacitance Measurement** Typical Capacitance Matching **Temperature Rating Dielectric Withstand Volage** 

X7R or COG Multiple capacitance At 1000hr point Better than 5% -55℃ to 125℃ 2.5 x Rated Volts for 5 secs. Charging current limited to 50mA Max. 10,000 Mohms Min Nickel Barrier

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**Insulation Resistance Termination Material** 

#### Advantages

- Replaces 2 or 3 capacitors with one device
- Matched capacitance line to ground on both lines
- Low inductance due to cancellation effect
- Capacitance line to line
- Differential and common mode attenuation
- Effects of temperature and voltage variation eliminated
- Effect of ageing equal on both lines
- High current capability
- Applications
- Balanced lines
- Twisted pairs
- EMI Suppression on DC motors
- Sensor/transducer applications
- Wireless communications Audio

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Cinp					
Size	L	w	т	L1	L2
0603*	1.6±0.2 (0.063±0.008)	0.8±0.2 (0.03±0.008)	0.5±0.15 (0.02±0.006)	0.3±0.2 (0.012±0.008)	0.2±0.1 (0.008±0.004)
0805	2.0±0.3 (0.08±0.012)	1.25±0.2 (0.05±0.008)	1.0±0.15 (0.04±0.006)	0.5±0.25 (0.02±0.01)	0.3±0.15 (0.012±0.006)
1206	3.2±0.3 (0.126±0.012)	1.60±0.2 (0.063±0.008)	1.1±0.2 (0.43±0.008)	0.95±0.3 (0.037±0.012)	0.5±0.25 (0.02±0.01)
1410	3.6±0.3 (0.14±0.012)	2.5±0.3 (0.1±0.012)	2 max. (0.08 max.)	1.20±0.3 (0.047±0.012)	0.5±0.25 (0.02±0.01)
1812	4.5±0.35 (0.18±0.14)	3.2±0.3 (0.126±0.012)	2 max. (0.08 max.)	1.5±0.35 (0.6±0.14)	0.5±0.25 (0.02±0.01)
2220	5.7±0.4 (0.22±0.016)	5.0±0.4 (0.2±0.016)	2.5 max. (0.1 max.)	2.25±0.4 (0.09±0.016)	0.75±0.25 (0.03±0.01)





#### **Insertion Loss Characteristics (common mode)** Typical 50 ohm system





1. For details of ordering see page 62 2. For soldering and installation information see page 69đ

The 0603 chip size is a development item that will be available during the life of this catalogue. All technical information should be considered provisional and subject to change.

Integrated Passive Components Balanced Line EMI Chip

100 120 150 150 220 270 330 390 470 560 680 820	(4) (4) (4) (4) (4) (4) (4) (4) (4) (4)	5pF 6 7.5 9	*0603	0805	1206	LALO	-BLC	2220
100	 10pF	5pF						
120	12	6	502					
150		715						
220	18 22	9 11 13.5 16.5 19.5 23.5 28 34 41 50 60 75 90 110 135 165						
270	27	13.5			<b>T</b>			
330	27 33	16.5			× ×			
390	39 47	19.5						
470	47	23.5						
560	56 68	28						
820	82	24 41						
101	100	50						
121	120	60						
151	120 150	75				Ž		
181	180	90						
221	220	110						
271	270	135						
331	330	105						
471	390 470	195 235 280		2				
561	560	280						
101 121 151 181 221 271 331 391 471 561 681 821 102 122 152 182 222 272 332 373 392 472 562 682 822 103 153 153 153 153 153 153 153 15	680	340 410 0.5nF						
821	820	410						
102	1.0nF	0.5nF						
122	1.2 1.5	0.6 0.75			<b>T</b>			<b>P</b>
152	1.5	0.75						
182	1.8 2.2	0.9						
222	2.2	1 35						
332	3.3	0.9 1.1 1.35 1.65 1.95 2.35 2.8 3.4 4.1				e e e e e e e e e e e e e e e e e e e		
392	3.9	1.95						
472	3.9 4.7	2.35						
562	5.6	2.8					Į	
682	6.8	3.4						
822 102	8.2 10	4.1						
123	10	5 6 7.5						<b>B</b>
153	12 15	7.5						2
183	18	9						
223	18 22 27	11						
273	27	13.5						
333	33	16.5						
393 473	39 47 56	9 11 13.5 16.5 19.5 23.5 28						
563	56	23.5						
683	68	34						
823	82	41						
104	100	50						
124	120	60						
154	150	75	Vol	tage				
184 224	180 220	90 110						
274	270	135		100V				
334	330	165		50V				
394	390	195		25V				
474	470	235						
564	560	280		) 16V				
684	680	340						
824 105	820 1µF	410 0.5µF						
105	1.2	0.5µF 0.6						
123	1.2	0.0						
Reeleo	d 178	mm (7")	4000	3000	2500	2000	1000	1000
Quant	city 330	mm (13")	16000	12000	10000	8000	4000	4000



1. For detail of ordering see page 62.



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## Integrated Passive Components Balanced Line EMI Chip

BLC

The Syfer Balanced Line EMI chip has a unique internal architecture which provides unbeatable EMC performance for dual line data transmission.



A typical application for dual line data transmission would see a board layout using decoupling chip capacitors or 3 terminal feedthrough chips as shown in Fig 1.



Fig 1

The Balanced Line EMI chip replaces decoupling capacitors or 3 terminal feedthrough chips on a 1 for 2 basis and provides line to line (differential mode) decoupling. Fig 2.





The internal structure furnishes a reduced inductance when compared to that of a conventional capacitor. This is a result of the novel internal electrode structure which inherently reduces the inductance by the cancellation effect of opposing currents in close proximity.

The capacitance line to ground (common mode) is closely matched due to the symmetry within the design. As the device includes line to ground capacitance for both lines, any temperature, ageing and voltage effects will have an equal influence on both lines therefore maintaining balanced decoupling.

The construction also allows a capacitance between lines as well as to ground as shown in Fig 3.



C2, the line to line capacitance, is half the line to ground capacitance thus providing coupling of high frequency interference between balanced lines.

Because the part acts as a decoupling device, the current limitations of a standard 3 terminal chip do not apply. The single line 3 terminal feedthrough chip carries the signal current through the very thin feedthrough electrodes within the device which have limited DC resistance and so can cause excessive heating, hence the maximum permissible current is often limited to around 300 mA for a 1206 device. The dual line 3 terminal chip is in by-pass across two lines and so is unaffected by high signal currents.

Table 1 offers a comparison of decoupling devices and demonstrates how the Balanced Line EMI chip extends the options for EMC circuit protection.

3 terminal feedthrough       • Feedthrough       • Current         • Very low inductance       • Current         • Replaces 2 (or 3) components       • Nanstea the offerte of	· · · · · · · · · · · · · · · · · · ·
feedthrough     • Lower Inductance     • Current       • Very low inductance     • Replaces 2 (or 3) components     • Not for	
Replaces 2 (or 3) components     Negates the effects of     Not for	nited  Feedthrough Unbalanced lines High frequency
Provides both common mode and differential mode attenuation	balanced signal lines balanced signal lines



### Integrated Passive Components Balanced Line EMI Chip

#### **Application Note**

One of the significant features of this product is its extremely low inductance, making it particularly suitable for high speed digital applications and for reduction of common mode currents for power line applications. Inductance cancellation, due to the effect of opposing current flow across the device, results in a typical line to line inductance of around 100pH, with a corresponding line to ground inductance of 50pH.

The Balanced Line EMI chip satisfies the need for high speed communications systems using balanced lines or twisted pairs offering low inductance (therefore high frequency operation), reduced board space, reduced component count and an unparalleled performance.

BLC

Ordering Information								
1206	J	100	0222	Μ	X	т	E03	
Reference J = N	Nickel Barrier	Voltage 016 = 16 volts 025 = 25 volts 050 = 50 volts 100 = 100 volts	Capacitance Expressed in picofarads (pF). First digit is 0. Second and third digits are significant figures of capacitance code. The fourth digit is number of zeros following. Example: 0222=2200pF.	Tolerance M= ±20%	<b>Dielectric</b> C = COG X = X7R	<b>Packaging</b> T = 178mm (7") reel R = 330mm (13") reel B = Bulk	Balanced Line EMI Chip	



 Technical and application papers are available on request from the Sales Office.

Manufactured in the UK by Syfer Technology Limited under licence from X2Y attenuators LLC.

